THE SINGER COMPANY
KEARFOTT DIVISION
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FINAL REPORT
FOR
SOLID STATE SWITCH PANEL

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## ABSTRACT

An intensive study of various forms of transducers was conducted with application towards hermetically sealing the transducer pick off and all electronics. The results of the study indicated that the Hall effect devices and a LED/phototransistor combination were the most practical for this type of application. Therefore, hardware was developed utilizing a magnet/Hall effect transducer for single action switches and LED/phototransistor transducers for rotary multiposition or potentiometer applications. All electronics could be housed in a hermetically sealed compartment. A number of switches were built and models were hermetically sealed to prove the feasibility of this type of fabrication. One of each type of switch was subjected to temperature cycling, vibration, and EMI tests. The results of these tests are indicated in the following report.

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RESULTS
The results of this project are:

1. An operating switch panel conforming to the requirements of NAS-9-13144.
2. Test data taken during environmental tests performed on selected switch and rotary components. The tests performed were comparable to tests run on NASA flight hardware delivered on the skylab project. Satisfactory results were obtained on all tests.
3. Reliability data indicating MTBF for selected devices.
4. A project report covering the study phase of the project and containing test data, schematics, and outline drawings of the switch devices and the mounting panel.

## CONCLUSIONS

The results of this project indicate that solid state switches and rotary components capable of meeting the requirements of manned space flight are feasable and well within the current state of the art. The environmental and reliability data indicate that a production unit would have the superior reliability associated with solid state equipment. The large selection of contact closure types will allow switches to be fitted to various requirements. A phase II production type unit would be packaged in a smaller and lighter housing. The feel of each switch and the front panel appearance would be improved in the phase II design.
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RECOMMENDATION
The study indicated that the most efficient switch is one designed to switch a specified voltage and current. Using a high current switch to handle a low current is inefficient. Any production switches should be designed for a specific power level.

In production quantities a hybrid package containing all the electronics is recommended as a way to save size and increase reliability of the solid state switch devices.

Reduction of switch size would allow the toggle section of the switch to be brought flush to the panel surface and otherwise improve the appearance of the switches.

It is also recommended that a closer analysis of the front panel removability criteria be made with an effort to reduce the panel area used for fastening.

## INTRODUCTION

The purpose of this report is to summarize the results of a study conducted to determine the optimum transducer type and output circuitry for a solid state switch configuration and to demonstrate with hardware, the feasibility of the resulting designs. Two basic types of switches are required, a single action switch (toggle, pushbutton) and a multiposition rotary switch and/ or potentiometer. The switches will be designed to be hermetically sealed and removable as an integral unit from the front of the panel. Selected switches contain a Light Emitting Diode (LED) display indicating the status of the switch position and/or operable or failure mode.

The various types of transducers studied included the following:

- Light
- Capacitive
- Hall effect
- Magneto-resistor

Many factors were considered in selecting the appropriate transducer for the application and the necessary circuitry for the switch output. They were as follows:

- Type of excitation required
- Power required
- Cost
- Size
- Reliability
- Hermetic sealing capability
- Cross talk effects
- Packaging
- Switching characteristics

A matrix indicating these characteristics of the various transducers are shown in Table I.

TABLE I. TRANSDUCER MATRIX

|  | LIGHT | CAPACITANCE | $\begin{aligned} & \text { HALIL } \\ & \text { EFFECT } \end{aligned}$ | MAGNETO RESISTOR |
| :---: | :---: | :---: | :---: | :---: |
| POWER | . 150 WATTS | .100 WATT | . 050 WATT | . 050 WATT |
| EXCITATION | DC 5-10V | AC 10 KHZ | DC 5-10V | DC 5-10W |
| COST | MODERATE | HIGH | LOW | MODERATE |
| CROSS TALK | NONE | PROBLEM AREA | NONE | NONE |
| HERMETIC SEAL | PROBLEM AREA GLASS TO METAL SEAL | PROBLEM AREA GLASS TO METAL SEAL | COMPATABLE | COMPATABLE |
| SIZE | MODERATE | LARGE | SMALL | MODERATE |
| COMPONENTS | TWO SILICON <br> SEMI-CONDUC- <br> TORS AND <br> GLASS SEAL | TWO SEALED METAL PLATES AND DRIVE CIRCUITRY | ONE INTEGRA- <br> TED CIRCUIT <br> AND MAGNET | ONE SEMICONDUCTOR AND DRIVE CIRCUITRY |
| SWITCHING CHARACTERISTICS | REQUIRES TRIGGER | REQUIRES TRIGGER | TRIGGER <br> PART OF IC | TRIGGER REQUIRED |

The results of the study indicated that the Hall effect transducer is the most effective for the single action switch and the LED/phototransistor is the optimum device for the multiposition rotary switch and potentiometer.

Dependent upon the function of the switch, four types of output circuits were selected to interface with peripheral equipment. The determining factor in the circuitry was the contact rating of the switch.

| - High current | DC | (10 AMP) |
| :--- | :---: | :--- |
| - Medium current | DC | $(400 \mathrm{MA})$ |
| - Low current | Analog | $(50 \mathrm{MA})$ |
| - Low current | AC | (I AMP) |

To insure reliable operation, redundant circuitry has been included wherever size and circuitry dictates practicability. The subject of man-hardware interface has not been discussed because standard mechanical switch actuating devices are used for inputs with normal actuating pressure loads and travel.

Envelope drawings and schematics are included in the appendices (Section 8) indicating the design approach configurations for the Phase I program. Production versions of these modules would require some modification for facility of fabrication and appearance. As a result of the study program, a panel was fabricated including 25 single pole or double pole toggle and pushbutton switches, two rotary 10 position switches and two potentiometers as indicated in Figure 1.
FIGURE 1 SOLID STATE SWITCH PANEL

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TECHNICAL DESCRIPTION
The following four basic areas were studied in order to produce the required switch/potentiometer configurations for the switch panel:

- Transducers
- Mechanical Packaging
- Output (switch contact) circuitry
- Solid state potentiometer circuit configurations


## TRANSDUCERS

Many types of transducers were evaluated to determine the optimum switch transfer. For each transducer the source and sensor of the switching medium is discussed along with the various configurations.

MAGNETIC CIRCUIT TRANSDUCER
A magnetic circuit transducer depends on changing magnetic flux for switching action. A mechanical switch change occurring external to the hermetic seal changes the reluctance of the magnetic circuit. This flux change is sensed inside the hermetic seal and interfaced with the logic section of the switch. Both alternating and direct flux devices have been reviewed.

## DC Devices

The flux flows in only one direction in a direct flux circuit and is a function of the following relationship.

$$
\Phi=\frac{M M F}{R}
$$

A change in the flux is sensed and a typical simple switch is illustrated in Figure 2. With the switch open as in Figure 2 a high reluctance air gap exists in the magnetic circuit. If the missing slug is moved into the gap, the reluctance is diminished. This increases the flux and changes the characteristics of the flux sensing element. Two sources of mmf appear most appropriate for switch applications: permanent magnets or solenoid coils. Permanent magnets require the following characteristics to be effective.
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- Small size
- High induction
- High demagnetization force

Of the present commercially available magnetic materials, the following best suit these characteristics:

- Ceramic permanent magnets
- ALNICO SERIES*
- Gecor*

The life characteristic of these materials (tame of retention of useful magnetic properties) has been estimated at approximately 15 years.

Solenoid coils require electrical power in order to operate. However, these devices utilize materials which are more readily available than magnets and do not require any special handing techniques as is sometimes the case with magnets. Of the flux sensing elements available the following exhibit the most suitable properties for switch application:

- Pick up coil
- Hall effect device
- Magnetic resistor
- Pick Up Coil - The simplest of the three devices is a pick up coil which is a coil of wire of many turns wound around the magnetic core. This coil does not require a gap in the magnetic circuit which greatly increases the reluctance and, therefore, reduces the magnetic strength required. Many magnetic materials can be used for this application. The greatest disadvantage of using a pick up coil in a direct flux circuit is the fact that a coil can only sense a change in flux. Therefore, an output voltage would only be available from the coil during switching transition. After the coil has reached a different steady state valve as a result of the new switch position no voltage is present at the coil. The logic necessary to sense these

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transient pulses is relatively simple, however, the problem exists in the initial start up procedure. The use of this device is limited to momentary switch applications where the switch mode of operation is in the normally off condition.

- Hall Effect Device - The Hall effect element is a semiconductor device that generates a voltage as a function of control current and magnetic field. As illustrated in Figure 3 control current is passed through one axis of the semiconductor. The Hall voltage will appear perpendicular to the control current at the edges of the semiconductor chip. This voltage will be a function of the magnetic flux passing through the chip perpendicular to both control current and the output voltage. In the switch application, this voltage is used to control the switch output. The advantages of the Hall effect device are:
- Small size
- Detection of steady state flux levels
- Life and reliability similar to silicon semiconductors

Because the Hall effect device has a relatively low output voltage (in the order of 50 mv ) an amplification stage is necessary as an interface between the transducer and the switch output circuitry. The control current required for the Hall effect device is approximately $5 \rightarrow 50 \mathrm{MA}$. The Hall effect device is made very thin (. 006 inches typical) in order to retain a high flux density across the Hall device in the on condition.

A device available from Honeywell Microswitch incorporates a Hall effect device and an amplifier and trigger circuit in one integrated chip. This device operates on low levels of flux and provides as an output two current sinks. In addition to being small and sensitive this magnetic switch requires very little power to operate ( 30 mw max. at 5 volts). This power level is equivalent or lower than most flux sensing devices made of discrete parts.

The device has been designed to operate over the standard Military temperature range $\left(-55^{\circ} \mathrm{C}-\cdots+125^{\circ} \mathrm{C}\right)$ and is available off the shelf from Micro-Switch. The device is sensitive enough that no specific flux path need be incorporated in the hermetic seal. The switch will sense


FIGURE 3
the presence of a small magnet at distance of .090 in . with any non-magnetic material between the magnet and the sensor. This feature will greatly simplify the process of hermetically sealing the final package.

- Magneto Resistor - Magneto resistors are solid state passive devices that change their resistance in the presence of a magnetic field. The devices are thin crystals of Indium Antimonide with electrical connections at both ends (Reference Figure 4a). The crystal is a semiconductor with a grid-like conducting material running perpendicular to the direction of the current flow. With no flux passing through the device current flows perpendicular to the conducting bands implanted in the semiconductor. Under these conditions the device exhibits its lowest resistance. If flux is allowed to pass through the device, the current is forced to travel a greater distance between conducting bands (Reference Figure 4b). The longer current path increases the resistance between the ends of the device. Typical ratios between maximum and minimum resistance are on the order of 13 to 18 for sensitive devices. The application of the magneto resistor is similar to the Hall effect devices in that they are mounted in the gap in the magnetic circuit. Magneto resistors have the following advantages:
- Small size
- Low power
- Life and reliability similar to silicon semiconductors

Power consumption of magneto resistors is a function of the input current and resistance and is, therefore, in the order of mw.

## Alternating Magnetic Flux Devices

Alternating magnetic flux can also be used to convey mechanical switch status through a hermetic seal. Switches of this type operate using transformer coupling. This method would require the use of AC signals inside the hermetic seal. Because AC signals must be generated to produce the alternating flux and later rectified to interface with the logic and switch sections, this method will consume more power and be more complex than direct flux circuits.


FIGURE 4

The only source of alternating flux convenient for use in this application is a coil of wire around the magnetic flux path. The optimum frequency at which the flux should oscillate will be a function of core losses in the magnetic circuit, the size of the oscillator, and the amount of radiated energy acceptable.

The greatest disadvantage to this type of design is the possible energy radiated to other switches and circuitry behind the switch. This radiation can be minimized to some extent by placing a magnetic shielding around the switch and EMI filters on the electrical lines, however, this would complicate both the packaging and the manufacture of the final switch.

All the sensors which sense direct flux also sense alternating flux. Of the three types discussed (pick up coil, Hall effect, magneto resistor), the pick up coil is the most adaptable to alternating flux. A transformer type switch using coils might operate as follows:


In the configuration above, coil $\mathrm{N}_{1}$ is not strongly coupled with coil $\mathrm{N}_{2}$. Coil $\mathrm{N}_{2}$ is a feedback circuit for the oscillator. With the slug removed from the magnetic path the feedback is insufficient to maintain oscillation. This results is a zero voltage output at the full wave rectifier. If the missing part of the core is placed into the magnetic circuit, coil $N_{1}$ is coupled to coil $\mathrm{N}_{2}$ providing feedback to the circuit. This causes the circuit to break into oscillations and provides a DC voltage at the full wave rectifier switching the latching logic.
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The selection of the material to form the magnetic core, is based on a number of factors.

- Magnetic properties
- Ease of machining
- Compatibility with switch housing material
- Ability to form hermetic seal.

A material of high relative permeability and low magnetic retentivity is most desirable. This would insure the greatest change in flux for a given magnet. Two materials appear best suited to this requirement.

1. Cold rolled armco Magnetic input iron.
2. Cold rolled electro-magnetic iron.

When properly heat treated these materials are easily machined and can be soldered or brazed in the normal fashion.

One other consideration must be made if alternating flux is to be used. Core losses must be kept to a minimum which will require either a laminated core or a ferrite core. Both of these cores would be difficult to hermetically seal and will complicate the machining and manufacture of the transducer unit.

## Transducer Evaluation

In the following section each of the sensors and sources are evaluated, thereby, allowing the best possible combination to be determined. A summary at the end of this section compares all the combinations.

Coil Source With Coil Sensor
This approach is not acceptable because of the inability of the coil sensor to detect a steady state flux. A memory device of some type would be required to hold the switch in either the on or off state after a change in the flux level. Such a transducer would be further complicated by the circuitry required to guarantee proper start up. When power is first applied to the switch, circuitry must be provided to set the memory in either the on or off position depending on the position of the moveable core section.
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Another disadvantage of this method is the coil source which dissipates electrical power to provide a steady state flux. Permanent magnets use no power to accomplish the same thing.

Coil Source With Hall Effect Sensor
A transducer of this type is feasible. It has two major disadvantages which make it less acceptable than other methods to be described.

1. Power must be supplied to both the coil and the Hall effect device for proper operation. This current would be on the order of 30 ma which is much higher than other types of transducers.
2. The Hall effect device puts out a low voltage (40-400 mv) when magnetic flux passes through it. This voltage level would have to be amplified in order to drive logic. The addition of an amplifier would consume more power and space in the final design and is therefore not desirable.

Coil Source With Magneto Resistor Sensor
A transducer of this type offers many advantages. The magneto resistor requires no control current as does the Hall effect device so the total power consumption will be smaller than the Hall effect. With a flux change of 10 kilogauss the magneto resister changes its resistance by a factor of 7 from its 0 kilogauss level. This change is enough to actuate logic without amplification. At worst a single transistor will interface between the transducer and the logic section.

The only drawback to this combination is the coil source which will draw current to generate the flux.

Permanent Magnet With Coil Pick Up
This method is unacceptable for reasons mentioned under coil source coil pick up.

Permanent Magnet With Hall Effect Device
This arrangement has the same drawbacks as the one using Hall effect with coil source. The only advantage is the fact that no current would be required to generate the flux.
$\qquad$
The complete transducer circuit is indicated as follows:


Permanent Magnet With Magneto Resistor
This combination is acceptable because the flux is generated without the use of power and the Magneto reșistor requires few additional components and uses little power.

The complete transducer is as follows:


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$\qquad$
Permanent Magnet With Micro-Switch Sensor (Hall Effect/Amplifier/ Trigger)

Because this device is very sensitive and comes packaged with a trigger and amplifier on the same chip it appears to be by far the most advantageous transducer. It is sensitive enough that no pole pieces would have to pass through the hermetic seal barrier. This would greatly simplify the sealing process. Furthermore, the device comes in a small package allowing the overall switch size to remain small.

The complete circuit is shown below:


Coil Source With Coil Sensor (ac)
A transducer operating with these components would require the following circuitry:


2-12

The variable inductive coupling between the output and the input controls the feedback to the oscillator. Thus, by changing the feedback, the oscillator can be driven out of oscillation. By rectifying the output and using this signal to control the logic section, switch operation can be made.

The following problems complicate this approach to the transducer problem.

1. The oscillation inherent in this type of switch will be difficult to shield from the outside world. Use of large RF filters would be difficult due to the small package size required.
2. The difficulty in hermetically sealing a low loss AC type core (laminated or ferrite) would necessitate use of a DC type core. This would force the oscillator to work at a higher power level to offset core losses.
3. Part count for this type of transducer would be high making a small package size difficult.

Coil Source With Hall Effect Sensor (ac)
This type of transducer would have all the drawbacks mentioned under coil source and coil sensor plus the following:

The Hall effect device must be placed in the path of magnetic flux requiring a gap in the core of the oscillator decreasing the coupling. The output from a Hall effect device would be a very small voltage (40-10 mv).

The Hall effect device requires a control current for operation which is an added power requirement not necessary with a coil pick up. This type of transducer is not acceptable because of the poor AC flux characteristics of the Hall effect device. A coil pickup is far superior in every respect for this application.

Coil Source With Magneto Resistor Pick Up
This transducer is unacceptable for the same reasons mentioned under coil source Hall effect device pick up.

## Conclusions

Of all the magnetic transducers discussed in this section, the most acceptable is the Honeywell magnetic switch used in combination with a permanent magnet. It is the best selection for the following reasons.
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- Low power
- Smallest size of any magnetic transducer
- Lowest component count.

LIGHT TRANSDUCERS
Transducers of this type will direct a beam of light from a light source through a shutter arrangement to a light sensor. Both light sensor and source will be contained inside a hermetic seal. The shutter arrangement will be external to the hermetic seal. By either allowing the light beam to strike the sensor or interrupting the light beam with the shutter, switch control of the light sensor can be obtained.


The shutter type of transducer would require that the hermetic seal wrap around the movable shutter. This means a transparent hermetic seal would have to be made at each side of the shutter. To avoid this complicated seal, an alternate configuration with a reflective surface can be used. In this method light is directed through a transparent hermetic seal towards a reflective surface. Upon striking the surface the light beam is directed back toward the light sensor through the same transparent seal through which it originally passed. In this way only one
transparent seal is required and both source and sensor can be placed in the same place. Switching is obtained by either reflecting or not reflecting the light beam back to the sensor. No moving parts are required within the hermetic seal.


## Light Sources

A beam of light can be obtained from the following sources:

- Incandescent lamp
- Light emitting diode
- Electro luminescent lamp

The following characteristics would be desirable in a light source:

- Small size
- High brightness
- Low power
- Long life

It would also be desirable to have the light eminate from a single point source. As the light must be gathered into a beam to pass to the detector a single point source would simplify this requirement.

- Incandescent lamps - A light source of this type satisfies the size and brightness requirements with no difficulty. Light intensities as high as 2,400 foot LAMBERTS can be obtained in package sizes as small as Figure 5. The drawbacks of this source are its power consumption and its limited life. There would be no way to conveniently replace the lamp because of the hermetic seal. This factor alone makes use of incandescent lamps PROHIBITIVE.
- Light emitting diode - Light emitting diodes satisfy most of the requirements. They are small, have a very long life time, moderate power consumption with moderate brightness. A further advantage of the LED source is its narrow frequency band of light output.

Many types of photo diodes and photo transistors are optimized for use at a single frequency. This means that the proper combination of LED and photo diode will make more efficient use of the light than a combination of photo transistor and any other light source.

LED's come in a variety of package sizes. The device pictured in Figure 6 would be most suited to the requirements of this application. This device was designed to be used with a particular photo transistor in high speed card and tape readers. The characteristics of this device are listed in Table II.

- Electro-Luminescent Lamps - This type of lamp would not be suitable for this application. Electro-luminescent lamps have very low brightness ( 20 fL ) and are better suited to surface illumination.


## Light Sensors

Light emitting diodes are the best choice for light sources so only sensors which interface with LED's will be considered. The following devices are specifically designed to interface with LED's.

- Photo - Diodes
- Photo - transistors


FIGURE 5


FIGURE 6

TABLE II. LIGHT EMITTING CHARACTERISTICS
ELECTRICAL CHARACTERISTICS ( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise noted)

| Characteristic | Fig. No. | Symbol | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Reverse Leakage Current <br> $\left(\mathrm{V}_{\mathrm{R}}=3.0 \mathrm{~V}, \mathrm{R}_{\mathrm{L}}=1.0\right.$ <br> Megohm) | - | $\mathrm{I}_{\mathrm{R}}$ | - | 50 | - | nA |
| Reverse Breakdown <br> Voltage <br> $\left(\mathrm{I}_{\mathrm{R}}=100 \mathrm{\mu A}\right)$ | - | $\mathrm{BV}_{\mathrm{R}}$ | 3.0 | - | - | Volts |
| Forward Voltage <br> $\left(\mathrm{I}_{\mathrm{F}}=50 \mathrm{~mA}\right)$ | 2 | $\mathrm{~V}_{\mathrm{F}}$ | - | 1.2 | 1.5 | Volts |
| Total Capacitance <br> $\left(\mathrm{V}_{\mathrm{R}}=0 \mathrm{~V}, \mathrm{f}=\right.$ <br> $1.0 \mathrm{MHz})$ | - | $\mathrm{C}_{\mathrm{T}}$ | - | 150 | - | pF |

OPTICAL CHARACTERISTICS ( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise noted)

| Characteristic | Fig. No. | Symbol | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Total Power Output <br> (Note 1) <br> (I$=50 \mathrm{~mA}$ ) |  |  |  |  |  |  |

The characteristics desirable for this application are:

- Small size
- Compatible with LED light sources
- High light sensitivity
- Low power consumption
- Photo Diodes - Photo diodes are $P$ on $N$ or $N$ on $P$ silicon function devices that generate a photo current in response to a beam of light focused on the sensitive junction.

Being composed of silicon, these devices are small, rugged and reliable. The photo-diode is the basic photo sensitive device in all of the photo transistor varieties, so in one form or another it will be used in any kind of light transducer. The current voltage curves for a typical photo diode are shown below.


The voltage and current levels are sufficient to drive the logic section without further amplification. However, if a photo transistor were used, lower light intensities would be able to drive the same logic section. This would mean lower power consumption in the LED.

- Photo-transistors - The photo-transistor uses a photo diode to generate base current for a normal transistor. This, in effect, amplifies the current sensitivity of the device by the $\beta$ of the transistor. There is no difference in package sizes between the photo diode and photo transistor, both can be obtained in packages as small as Figure 6.

Photo FETS take advantage of the photo voltaic effect of photo diodes. This is the change in output voltage as a function of light intensity of an open circuited photo diode. The increase of current gain available using a photo $F E T$ is of the same order of magnitude as that of a photo-transistor.
$\qquad$
Configurations - The simplest configuration of a light transducer would look as follows:


In this configuration the light from the LED provides base current for the photo transistor turning it on. The shutter can be placed in the path of the light beam turning off the transistor.

The LED must be provided with from 20 to 50 ma of current depending on the distance between the diode and the transistor, the load RL on the transistor, and any attenuating devices between the diode and the transistor (glass, light pipes, etc.).

The configuration of the reflective type transducer would be identical to that pictured above except for the shutter which would become a mirrored surface.

## Conclusions

Of the light type transducers the light emitting diode in conjunction with the photo-transducer is the only method which will adequately meet the requirements of this application.
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Table III below lists the characteristics of this type of transducer.

TABLE III. LIGHT TRANSDUCER CHARACTERISTICS

| POWER | .150 WATTS |
| :---: | :--- |
| COMPONENT <br> COUNT | 3 |
| CROSS <br> TALK | NONE |
| EXCITATION | DC-5-10V |
| HERMETIC <br> SEAL | PROBLEM AREA <br> GLASS TO METAL <br> SEAL |

## CAPACITANCE TRANSDUCERS

A transducer of this type would operate by sensing the change of a capacitor and operating a trigger circuit from this change. Because all electrical components must be contained inside a hermetic seal the only portion of a capacitor which could be used to change the capacitance would be the dielectric. The plates of the capacitor being current carrying devices must lie within the hermetic seal and are therefore inaccessable for mechanical change.

This factor makes it very difficult to implement this type of transducer. Both plates must be sealed behind at least . 050 thick sheets of glass while the dielectric contained within the environmentally sealed section is moved in or out of the plate gap.

A further complicating factor is the dielectric itself. It would be desirable to have the capacitor make a very large change in capacitance. This would mean using a material with a high dielectric constant. Most materials with this characteristic are unacceptable for use in a space cabin environment.

A variable capacitance transducer is therefore unacceptable for use in this application.

## CIRCUITRY

## SINGLE ACTION SWITCH

The basic circuitry of the switch consists of a magnet and Hall effect transducer, amplifier and output solid state relay switch as shown in schematic SW201 (Appendix I). The Hall effect device is an integrated hybrid chip containing the Hall effect pick off, an amplifier and a Schmitt trigger. The output of the Schmitt trigger drives a transistor amplifier which supplies current to the coil of the solid state relay switch. The output of the solid state relay directly supplies the load. The solid state relay coil is in series with the transistor driver and a light emitting diode. The light emitting diode provides an indication that the switch is in the ON condition and that approximately 80 percent of the circuitry is operating normally. The only difference between the single pole and double pole switch is the addition of a solid state relay, the coil of which is in series with the original solid state relay coil, and an increased supply voltage to provide additional drive power.

TEN POSITION ROTARY SWITCH
The circuitry of the ten position rotary switch is shown in Schematic RDOOl (Appendix I). Four LED - phototransistor transducers provide the initial BCD triggering to obtain 10 discrete switch position outputs. The output of the phototransistors provides triggers to exclusive or gates which inserts the proper logic format into a BCD to one of ten decoders. The output of the decoder supplies through transistor amplifiers the current to drive the appropriate coil of solid state relay matrix. The output of the solid state relay directly supplies the load.

POTENTIOMETER
The input to the potentiometer consists of 7 LED - phototransistor transducers providing a resolution of 128 bits. The output of the phototransistors provides logic states to exclusive or gates, the outputs of which supply the necessary binary data to the digital to analog decoder. The decoder utilizes a ladder network with an operational amplifier output. The output is a 0 to 10 volt analog voltage capable of supplying a 1000 ohm or greater load. A visible LED on both the rotary switch and potentiometer indicate that all internal LEDs are energized.

## OUTPUT SWITCH CIRCUITRY

The output characteristics of the switches are tabulated in Table IV. Physically all chips are the same size so that any possible combination of switch outputs is available. An important consideration with all types of switches is that the input to output isolation impedance is in excess of $10^{\prime \prime}$ ohms.

## SWITCH CONFIGURATION

The following types of mechanical packages must be produced to comply with the contract.

- Toggle switch (maintained)
- Toggle switch (momentary)
- Push button
- Potentiometer
- Rotary switch

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TABLE IV. SWITCH CHARACTERISTICS

| SWITCH <br> TYPE | 100 MA <br> DC | 140 V <br> AC | 28 V <br> AC | 400 MA <br> DC |
| :--- | :--- | :--- | :--- | :--- |
| LOAD <br> VOLTAGE | +50V MAX <br> PEAK | 140 VAC <br> RMS | 280 VAC <br> RMS | 60 VDC |

INPUT (CONTROL) SPECIFICATIONS

| CONTROL <br> VOLTAGE RANGE | $3.8-10$ <br> VDC | $3.8-10$ <br> VDC | $3.8-10$ <br> VDC | $3.8-10$ <br> VDC |
| :--- | :--- | :--- | :--- | :--- |
| MAX INPUT <br> CURRENT @ 5V | 22 MA DC | 15 MA DC | 15 MA DC | 15 MA DC |
| TURN OFF <br> VOLTAGE (MAX) | 0.4 VDC | 0.8 VDC | 0.8 VDC | 0.4 VDC |
| DIELECTRIC <br> STRENGTH <br> INPUT TO OUTPUT | 1000 VAC <br> (PP) | 2500 VAC <br> (RMS) | 2500 VAC <br> (RMS) | 1500 VAC <br> (PP) |
| ISOLATION <br> INPUT TO OUTPUT | $10 " \Omega \mathrm{MIN}$ | $10^{\prime \prime} \Omega \mathrm{MIN}$ | $10^{\prime \prime} \Omega \mathrm{MIN}$ | $10 " \Omega \mathrm{MIN}$ |

OUTPUT (LOAD) SPECIFICATIONS

| OUTPUT CURRENT RATING | $+100 \mathrm{MA}$ | 1.0 AMP | 1.0 AMP | 400 MA |
| :---: | :---: | :---: | :---: | :---: |
| OUTPUT <br> VOLTAGE | $\begin{aligned} & +50 \text { MAX } \\ & { }_{\text {PEAK }} \end{aligned}$ | $\begin{aligned} & 140 \text { VAC } \\ & \text { RMS } \end{aligned}$ | $\begin{aligned} & 280 \text { VAC } \\ & \text { RMS } \end{aligned}$ | 60 VDC |
| OFFSET <br> VOLTAGE | $\frac{+5.0}{\bar{M} A X}$ | - | - | - |
| CONTACT "ON" <br> RESISTANCE (OHMS | 5.0 MAX | - | - | - |
| CONTACT "OFF" RESISTANCE (OHMS | $10^{9} \mathrm{MIN}$ | $2 \times 10^{5}$ | $\begin{aligned} & 2 \times 10^{5} \\ & \text { MIN } \end{aligned}$ | $\begin{aligned} & 10^{7} \\ & \text { MIN } \end{aligned}$ |
| MAX DRIVE FREQUENCY (Hz) | 100K | 500 | 500 | 30K |
| MAX SURGE RATING | 0.1 JOULE | 10 AMP | 10 AMP | - |
| CONTACT VOLTAGE <br> DROP AT RATED <br> CURRENT (MAX) | 250 MV | 1.5V RMS | 1.5V RMS | 1.5VDC |

$\qquad$
Each type must have the electronics hermetically sealed. The packages for each type therefore have two sections, a hermetically sealed section and an environmentally sealed section. The hermetically sealed section contains the drive electronics. The mechanical actuation is contained in the environmentally sealed section.

There are two basic types of package. One contains all the single action switch configuration and the other houses the rotary switch and potentiometer.

## SINGLE ACTION SWITCH

The single action switch is packaged in a rectangular case of the same approximate dimensions as the present hermetically sealed single pole double throw mechanical switch made by Texas Instruments for the LEM and Apollo missions.

Of all approaches tried, Hall effect devices and magneto resistors were the most acceptable. The Hall effect device, because of the higher sensitivity of the Micro-switch device, results in no pole pieces extending through the hermetic seal and, therefore, is the optimum selection.

Figure 7 depicts the layout of the single action switch using this Hall effect device.

POTENTIOMETER AND ROTARY SWITCH
A potentiometer with a resolution of 3.6 degrees is provided. The potentiometer is not a variable resistor but a variable voltage supply which should serve all the functions normally performed by a potentiometer. Rotation of the pot shaft varys the digital input to a D to A converter (DAC) producing a variable voltage. The pot is, in effect, a 7 bit encoder connected to a DAC.

The encoder portion of the potentiometer is a mirrored disk outside of the hermetic seal. Inside the hermetic seal a series of photo diodes and light emitting diodes operating through a transparent seal senses the position of the mirrored disk. This digital information is connected to a DAC to provide the output.

The rotary switch is of the same configuration as the potentiometer. An encoder disk is mirrored into 10 sections. A series of photo diodes and light emitting diodes senses the position of the encoder disk and operates 10 individual switches. Any of the switch outputs shown in Table IV can be provided in the rotary switch.


FIGURE 7. SOLID STATE TOGGLE SWITCH OUTLINE DRAWING (Sheet 1 of 2)


# FIGURE 7. SOLID STATE TOGGLE SWITCH OUTLINE DRAWING (Sheet 2 of 2 ) 

$$
2-28
$$

The potentiometer and rotary switch are both packaged in a cylindrical housing approximately 2.5 inches in diameter and 1.5 inches in depth. Figure 8 depicts the layout for the solid state pot and rotary switch. A glass seal separates the hermetic section from the encoder wheel. The encoder wheel is environmentally sealed at the shaft with an 0-ring. Light from the LEDs passes through the glass seal, is reflected by the silvered encoder disk and after again passing through the glass seal turns on the phototransistor. Seven LED phototransistors are arranged to align with a Gray code disc providing seven bits of non-redundant binary information. This information is converted into a variable voltage in the D to A section located on the two PC boards in the sealed area.

## HERMETIC SEAL

A sample of each package style is hermetically sealed. The hermetically sealed portions of these packages constructed as gas tight enclosures completely sealed by fusion of glass to metal or bonding of metal to metal. Special sapphire glass discs already hermetically sealed to a metal ring are brazed into the brass casing to provide the chamber hermetic seal. After the electronics are inserted into the chamber and leads attached to the soldered glass/metal interconnect the back cover is soldered into place. Prior to sealing, the enclosure is cleaned and dried. The enclosure is purged of all air and backfilled with one atmosphere of gas consisting of 95 percent nitrogen/5 percent helium. A primary consideration in the selection of enclosure materials is the ease of welding, brazing or soldering the bonding methods typically employed for metal to metal hermetic seals. Final material selection provides for brass casings for ease of brazing and soldering.

## Environmental Seals

Environmental sealing is accomplished primarily by gasketing. Silicone 0 -rings and gaskets are utilized at closure points to prevent dirt or moisture infiltration and other contaminants.

PANEL CONFIGURATION
The sold state switch panel contains the following types and quantities of switches.

$$
\begin{array}{lll}
\text { Toggle maintained } & \text { SPST } & 5 \\
\text { Toggle maintained } & \text { DPST } & 5
\end{array}
$$



FIGURE 8. SOLID STATE POTENTIOMETER (Sheet 1 of 2)
$\qquad$


FIGURE 8. SOLID STATE 10 POSITION SWITCH (Sheet 2 of 2)
$\qquad$

| Toggle momentary | SPST | 5 |
| :--- | :--- | :--- |
| Toggle momentary | DPST | 5 |
| Pushbutton | SPST | 3 |
| Pushbutton | DPST | 2 |
| Rotary | 10 position | 2 |
| Potentiometer |  | 2 |

These switches are mounted on a 19-inch wide rack. Two of these switches control high powered 10 amp switches mounted directly on the test panel. The test panel also contains the rated loads for all the switches and potentiometers and provides an indication as to which switches are being operated. The switches are grouped relative to contact rating and identified accordingly on the test panel.

## SUMMARY

For the small number of switches produced, several techniques were utilized which would not necessarily remain in the production unit. The same housing was used for both pushbutton and toggle switches which necessitated the use of an add-on toggle assembly. In production units, the toggle assembly would become an integral part of the switch body thereby enhancing the usual outline of the toggle switch.

In production quantities, all switch and rotary components would be hybridized to miniaturize the electronics. This would diminish the package size and simplify hermetic sealing.

## POWER CONSUMPTION

Excluding the switch contact ratings, the following power is required in the quiescent (non-operating) state and the operating mode for each type of switch.


PANEL OPERATION
POWER APPLICATION
Place all switches in the off (down) position. Apply the power to the proper pins on the input jack panel located at the bottom of the switch panel. The positive side of the -12 volt input connects to the black input jack and the negative connects to the red jack. The 28 power supply shall be capable of suppling 25 amps in order to test the power switches.

The AC voltages ( $120 \mathrm{VAC}, 240 \mathrm{VAC}$ ) are only used to provide contact voltage ratings on the 5 pushbutton AC switches. The AC need not be connected for proper check out of all DC switches and rotary components.

OPERATION
The switch labeled panel controls power to the entire panel. Power is connected to this switch whenever power is present on the jack panel. When it is switched to the ON position, power is applied to all other switches.

With power connected to the panel and the panel switch on, all switches will operate. Switching any toggle momentary or maintained to the ON (up) position or operating any pushbutton will cause the appropriate load light to illuminate. For the two power switches there are no load lights. Closure indication for these switches is given by two current meters located at the top of the panels.
$\qquad$

The rotary devices are also actuated by the panel switch. The outputs of the potentiometers are indicated by two volt meters located at the top of the panel. The rotary switches are connected to decimal displays which indicate the position of the switch.

LOAD CONNECTOR PIN OUT.


TESTS
FUNCTIONAL TESTS
All switches were tested at standard ambient conditions to insure proper operation at rated voltage and 10 percent under and over voltages. Power at nonoperating (quiesent) and operation conditions were measured for the entire panel with the following results:

| Panel Quiesent Power | 2.4 Watts |
| :--- | ---: |
| Panel Operating Power | 14.7 Watts |

The panel operated satisfactorily when submitted to the various functional tests.

## ENVIRONMENTAL TESTS

One type of each switch: toggle, pushbutton, rotary and potentiometer were submitted to the following environmental tests.

## TEMPERATURE

2 Hour Soak at $0^{\circ} \mathrm{C}$
Functionally tested
2-Hour Soak at $70^{\circ} \mathrm{C}$
Functionally tested

## RESULTS

SPST, DPST, and Rotary Switch operated satisfactorily. Potentiometer intermittent at high temperature as a result of low current through LED's. Increasing current through LED's provides stability over temperature range, however, higher power dissipation results.

## RANDOM VIBRATION

## Procedure

A random vibration equal to the total $G$ level utilized on the LEM and Skylab was impressed on the switches. Period of application is 2 minutes.

$$
1150-2000 \mathrm{~Hz} \quad 20-2000 \mathrm{~Hz} .02^{\mathrm{gr}} / \mathrm{Hz}
$$

$\qquad$
Switches Tested
Pushbutton
Toggle
Rotary Switch

## RESULTS

A1l switches functioned throughout the random vibration. The pushbutton normally open remained in the normally open state, the toggle maintained in a closed switch position remained in that state without interruption and the rotary switch set at position 5 remained closed in that position with all other positions normally open. The graphs on the following pages visually depict the vibration levels applied in the during the test.

## EMI TESTS

EMI tests were conducted on the double pole, single pole and the potentiometer in accordance with MIL-STD-461. The tests performed were CE01, CE03 and CS06. CE01 and CE03 were preformed on every lead of the device under test. CS06 was preformed on all power leads with the spike equal to $50 \%$ of the nominal line voltage.

RESULTS
The results of the CEOL \& CEO3 tests are contained in the attached data. Emissions for all devices were within the $\max$ specification limit. All devices operated successfully during the CS06 tests.





Y256A226 REV $\qquad$




Y256A22 $\quad$ REV $\qquad$


Electromagnetic Compatibility Test Data Sheet
NASA

TEST MODE


NOTE: A - All frequencies not listed are stoned for maximum interference.
A - Interference Type: (I) Srocibond, Steady-Srote
(3) Norrowtand (CW)

Electromagnetic Compatibility Test Data Sheet


NOTE: A - All frequencies not listed are scanned tor maximum interlerence.
$\begin{array}{ll}\text { B - Interference Type: } & \text { (1) Broodband, Sieody-State } \\ & \text { (2) Broosbond, Transients } \\ & \text { (3) Norrowband (CW) }\end{array}$

Electromagnctic Compalibility Test Data Sneet


NOTE: A - All frequencies not listed are scanned for maximum inferference.
A- interference Type: (1) Eroadband, Steady-State
(2) Broadband, Tronsients
(3) Norrowbend (CM)

Electromagnetic conpatibitity rest mata shect


SER No.

POWER ON


NOTE: A - All fequencies not listed are sconned for masimum interference.
B - Interlerence Type:
(1) Beoadband, Steody-Stote
(2) Broodband, Transients
(3) Norrowbond (CW)

Electromagneflc Compatibility Test Data Sheet

MODEL NO
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SERNO.


NOTE: A - All frequancies not listed are scenned for maximum interlerence. B - inierference Type:
(1) Broadband, Steody-State
(2) Broathand, Transients
(3) Nartowband (CW)



## Electromagnetic Compatibility Test Data Sheet



NOTE: A - All trequencies not listed ore scorined lor maximum interference. B - Intorference Type:
(1) Broodband, Steady-State
(2) Broodbond, Trensients
(3) Nartowband (CW)

Electromagnetic Compatibility Test Data Sheet



NOTE: A - All frequencies not listed ore scanned far maximum interference.
B - Interference Type: (i) Broadband, Sieady-Stale
(2) Broodbond, Transients
(3) Narrowbond (CW)

## Electromagnetic Compatibility Test data She et

TEST SPECIMEN

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\text { NASA } \quad \text { MODEL NO } 0-1-2
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NOTE: A - All frequencies not listed are scanned for maximum interference.

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\begin{array}{ll}
\text { B - Interference Type: } & \text { (1) Broadband, Sieady-Stere } \\
& \text { (2) Broadband, Transients } \\
& \text { (3) Narsowbond (CW) }
\end{array}
$$

## Efectromagnetic compatibility Test Data Sheet



$$
N A S A
$$

MODELNO
$0-1-2$
TESTMODE

$+$


## NOTE: A - All frequencies not lizted are sconned for maximum interference.

$\begin{array}{ll}\text { B - Interlerence Type: } & \text { (1) Erocdbond, Steady-State } \\ & \text { (2) Broadbond, Trensients }\end{array}$
(3) Narrowband (CW)

Electromagnetic Compatibility Test Data Sheet

| TEST SPECIMEN | $\mu A S A D C$ | BLE PO | $\left.C E\right\|^{\text {MODELNO }}$ | $0 \% 2$ |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
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| conoucteo ar | A.6. | ${ }^{\text {OTTE }}$ | 17.73 ${ }^{\text {CHEC }}$ |  |  | -0.76, 1-17-73 |
| $\xrightarrow{\text { TESET }}$ | ${ }_{\text {REESEING }}^{\text {MEI }}$ | $\xrightarrow{\text { CORRECTION }}$ EACTOP | ${ }_{\text {REAPALIG }}^{\text {EIN }}$ | ${ }_{\text {SPECIFICATION }}^{\text {LIMIT }}$ | $\xrightarrow{\text { NTYER. TYP }}$ | Remarks |
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| . 620 | 43 | " | 54 | $1 \cdot 4$ | 1 | PROTE |
| -1.025 | 42 | 10 | 52 | 120 |  |  |
| $\underline{035}$ | 32 | 7 | 39 | 116 |  |  |
| - 0.45 | 34 | 5 | 39 | $1 / 2$ |  |  |
| . .665 | 32 | 4 | 36 | 106 |  |  |
| . 088 | 30 | 3 | 33 | 102 |  |  |
| . 10. | 30 | 2 | 32 | 98 |  |  |
| . 120 | 30 | 1 | 31 | 96 |  |  |
| -159 | 30 | 1 | 31 | 92 |  |  |
| - 200 | 30 | 0 | 30 | 87 |  |  |
| - 300 | 30 | 0 | 30 | 80 |  |  |
| - | 30 |  | 30 | 76 |  |  |
| . 500 | 55 |  | $55^{\circ}$ | 72 |  |  |
| . 800 | 30 |  | 30 | 6.4 |  |  |
| 1.0 | 30 |  | 30 | 60 |  |  |
| 1.5 | 35 |  | 35 | 59 |  | ! |
| 2.0 | 30 |  | 30 | - 50 |  | 3 |
| 4.0 | 30 |  | 30 | - ${ }^{\text {- }}$ |  | 1 |
| 4. 0 | 30 |  |  |  | I |  |
| 5.0 | 55 |  | 55 |  |  |  |
| 6.0 | 37 |  | 37 |  |  |  |
| 9.2 | 38 |  | 38 |  |  | I |
| 12.0 | 30 |  | 30 |  |  | : |
| 15.0 | 30 |  | 30 |  |  |  |
| 20.0 | 30 |  | 30 |  |  |  |
| 36.0 | 30 |  | 30 |  |  |  |
| 40.0 | 30 |  | 30 |  |  |  |
| 55.0 | 37 | $V$ | 37 | $\checkmark$ | $\downarrow$ | $\checkmark$ |
|  |  |  |  |  |  |  |
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NOTE: A - All frequencies not listed are sconned for maximum intarference.
B - interierence Type:
(1) Broodbond, Sready-Stote
(2) Broodband, Transients
(3) Narrowbend (CW)

Electromagnetic comgatibilliy Test Data Sheef
NASA

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$$

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| .063 |
| ---: |
| .080 |
| .100 |
| .120 |
| .1500 |
| 1.500 |











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NDTE: A - Alt frequencies not listed afa scanned for maximum interference.
$\begin{array}{cl}\text { A - All frequencies not listed ara scanned for maximum } \\ \text { B-Intefference Type: } & \text { (1) E.oodbond, Seady Stote } \\ & \text { (2) Broodband, Transients } \\ & \text { (3) Norrowband (CW) }\end{array}$


NOTE: A - All frequencies not listed ore sconned for moximum interference.
B - Interference Type: (1) Breodbend, Steady-Stote
(2) Broadbend, Tronsients
(3) Narrowband (CW)

Electromagnetic Compatibilliy Test Data Sheet


NOTE: A - All frequencies not listed are scanned for maximum interference.
B - Inierlerence Type:
(1) Broadband, Steady-Siate
(2) Broodband, Tronsients
(3) Narrowband (CW)

Efectromagnetic Compatibillty Test Data sheef


NOTE: A - All frequencies not listed are sconned for maximum interference.
B - intefference Type: (1) Broodbend, Steady-Stote
(2) Broodbond, Transients
(3) Norrowband (CW)

Efectromagnetic Compaflbility Test diata Sheef


NOTE: A - Alt frequencies naf listed are scanned for maximum interference.
8-Interference Type:
(1) Broadband. Steody-Store
(2) Broodbend, Tronsients
(3) Norrowbend (CW)

Electromagneilc Compatibility Test Data Sheet


| SPECIMEN |  |  |
| :---: | :---: | :---: |
| $N A S A$ | MODEL NO | $0-1-2$ |

Powtic oi


NOTE: A - All frequencies not lisped are scanned for maximum interterence.

$$
\begin{array}{cl}
\hat{B}-\text { Interference Type: } & \text { (1) Boodband, Stecody Stote } \\
\text { (2) Broodbond Tranternt3 }
\end{array}
$$

Electromagnefic Compatibllity Tes: data Sheet


NOTE: A - All trequencies not listed are sconned for maximum interference.

$$
\begin{array}{cl}
\text { B - Interlerence Type: } \\
& \text { (1) Broalband, Steady-State } \\
& \text { (2) Broodband, Tronsionts } \\
& \text { (3) Narrowband (CW) }
\end{array}
$$

Electromagnetic Compatibilliy Test data Sheef


NOTE: A - All frequencies not listed ore sconned lor moximum interference.
B = Interference Type: v(i) Broaibond, Steady-Sicte
(2) Broodbond, Transients
(3) Narrowbond (Cw)

Electromagnetic Compaflbilliy Test Data Sheet


NOTE: A - All frequencies not listed are sconned for maximum interferente.
$\begin{array}{ll}\text { B = Interlerence Type: } & \text { (1) Broodband, Steody State } \\ & \text { (2) Broodbond, Transients } \\ & \text { (3) Narrowbend (CW) }\end{array}$

Electromagnetic Compatibility Test Data Sheet

| TEST SPECIMEN $A$ |
| :---: |
| $N A S A$ |
| TEST MOE |

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$$
0-1-1
$$

sir no.

TEST MODE
Poufs ON


NOTE: A - All frequencies not listed ere scanned for maximum interference.
$B$ - Interference Type: $V(1)$ Broadband, Sieady-5taie
(2) Broadband, Transients
(3) Merrawband (CW)

Electromagnetic Compatibllity Test Daia Sheet


NOTE: A - All frequencies not listed are scanned for maximum interference. $\begin{array}{ll}\mathbf{B} \text { - Inierference Type: } & \text { (1) Broadbend, Steady-State } \\ & \text { (2) Broodband, Tronsients } \\ & \text { (3) Norrowbend (CW) }\end{array}$

Electronagnetic Compatibility Test Data Sheet


NOTE: A - Alf frequencies not listed are scanned for maximum interference.
B - Interference Type: (1) Broadbend, Steody-State
(2) Broadband, Tronsients
(3) Narrowbond (CW)

Electromagnetic Compatibitity Test Data Sheef
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$\frac{\text { Powere on }}{\text { specification }}$
PARAGRAPH $\left\lvert\, \begin{aligned} & \text { TEST } \\ & \text { OUT, } \\ & \text { OUT }\end{aligned}\right.$



NOTE: A - All Irequencies nor listed are sconned lor maximum interference.

- Intefference Type: (1) Broodband, Steody-5tote
(2) Broodband, Tronsients
(3) Narrowbond (CW)


## Electromagnetic Compallbility Test Data Sheet



NDTE: A - All frequencies not listed ora sconned for moximum interference.

## B-Interference Type:

(1) Broodband, Steody-Stote
(2) Broodbend, Trensients
(3) Norrowbend (CW)







$\qquad$
RELIABILITY
A reliability prediction was preformed to establish the failure rate of each of the solid state switch devices. This data is summarized on the attached computer data sheets. Also included in this section is a reliability failure mode and effects analysis. This analysis was made on the 10 position rotary, potentiometer, and the double pole switch.

## FIXED GRUUND ENVIRONMENT

## SUUASELMBLY -- GIRCUIT BUAKD $=1$

AMBIENT TEMPERATURL $=\quad 40 \mathrm{C}$


SUGASSEMBLY -- CIRCUII BLARO =2

|  | PART TYPE <br> CIRCUIT BUARU | $\begin{aligned} & \text { WUANT ITY } \\ & \text { 1.0 } \end{aligned}$ | $\begin{aligned} & \text { K(ENV) } \\ & 1.0000 \end{aligned}$ | $\begin{gathered} F R \\ 0.0630 \end{gathered}$ | $\begin{array}{r} \text { U.F.K } \\ 0.0630 \end{array}$ | $\begin{gathered} \text { STRESS } \\ 10 \end{gathered}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | DIUE | 4.0 | 1.5000 | 0.2000 | 1.5000 | 20 |
|  | LED |  |  |  |  |  |
|  | TRANSISTUR NPN | 4.0 | 1.5000 | 0.1975 | 1.1850 | 10 |
|  | PhOTOTKANSISTOR |  |  |  |  |  |
|  | TRANSISTOR NPN | 7.0 | 1.5000 | 0.1975 | 2.0737 | 10 |
|  | RES COMP RC | 11.0 | 6.0000 | 0.0035 | 0.2310 | 10 |
|  | RES CUMP RC | 1.0 | 0.0000 | 0.0035 | 0.0210 | 25 |
| HI-R | INTEGRATED CIRCUIT | 1.0 | 1. 2000 | 0.0300 | 0.0300 | 10 |
| HI-R | INTEGRATEO CKTIMSI | 1.0... | 1. 2000 | 0.0600 | 0.0720 | 10 |
|  | - SUBASSEMBLY TDT | AL - - |  |  | 5.242 | - |



## FIXEL GKUUNG EIVAIKLNMEAT

 SUBASSEMBLY -- SWITCH ASSY| AMBIENT TEMPERATURE $=$ |  |  | 40 C |  | STRESS 16 |
| :---: | :---: | :---: | :---: | :---: | :---: |
| $\begin{aligned} & \text { PART TYPE } \\ & \text { SHAFT } \end{aligned}$ | $\begin{aligned} & \text { GUANTITY } \\ & 1.0 \end{aligned}$ | $\begin{aligned} & \text { K(ENY) } \\ & 1.0000 \end{aligned}$ | $\begin{gathered} F R \\ 0.3500 \end{gathered}$ | $\begin{array}{r} 0 . f . K \\ 0.3500 \end{array}$ |  |
| BEARING | 3.0 | 1.0000 | 0.5000 | 1.5000 | 10 |
| DIODE | 1.0 | 1.5000 | 0.4175 | 0.6262 | 40 |
| LED | ..-- ... |  |  |  |  |
| SUBASSEMBLY TUTAL |  |  |  | 2.470 |  |


$\qquad$
$\qquad$


SUtiASSEMBLY -- RUTAKy SW Li pus



SUBASSEMELY -- PC bOAKD = 1
AMEIENT TEMPERATURE $=\quad 400$

$\qquad$
$\qquad$




SUGASSEMBLY - Suliu STatt fOT


FIXED GKOUND ENVIRONMENT
SUBASSEMBLY -- TUGGLE SWITCH SP

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-. . . . .-. . .-. .-.


FIXEO GKOUND ENVIROMMENT
EGUIPMENT -- SOLID STATE KEYOUAKD
AMBIENT TEMPERATURE $=\quad 40 \mathrm{C}$

| PART ROTARY | $\begin{aligned} & \text { TYPE } \\ & \text { SW } 10 \text { POS } \end{aligned}$ | $\begin{gathered} \text { OUANIIIY } \\ 2 . \end{gathered}$ | $\begin{aligned} & \text { K(ENY) } \\ & 1.0000 \end{aligned}$ | $\begin{gathered} F K \\ 10.2070 \end{gathered}$ | $\begin{array}{r} \text { U.F.K } \\ 20.4140 \end{array}$ | $\underset{10}{\text { STRESS }}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SOLID | state rut | 2. | 1.0000 | 4.1723 | 18.3447 | 10 |
| TOGGLE | SWITCH SP | 10. | 1.0000 | 2.2947 | 22.9475 | 10 |
| TUGGLE | SWITCH DP | 15. | 1.6000 | 2.2992 | 34.4887 | 10 |
| $\cdots$ | - . | - | -- |  |  |  |
|  | TUTALS |  |  |  | 96.195 |  |

## NuV. 8,1973

ह/time profile
TEMPERATURを/TIME PROFILE
PERCENT OF TIME AT TEMPERATUKE
1.0000

EQUIVALENT PROFILE FAILURE KATE $=96.1948$
PROFILE MTBF $=10395.57$ HOURS
$\stackrel{\stackrel{\rightharpoonup}{i}}{\stackrel{1}{n}}$

## EQUIPMENT -- SULID STATE KEYBLARD

AMBIENT TEMPERATURE $40 C$

- :

FIXED GRUUND ENVIRUNMENT

- PREDICTION BY PART TYPE


> JUUKCC OF UATA

PREDICTED SUGASSEMELY PREDICTED SUBASSEMBL PREDICTED SUBASSEMBLY PREDICTEC SUBASSEMELY

PREOICTEL SUBASSEMBL
PREDICTEC SUBASSEMBLY
PREDICTED SUBASSEMBLY
MIL-HDBK-217A FIGURE 7.4 .38 (MIL-S-29500)

NINTH SYMPOSIUM (EARLES/EDDINS)
MIL-HDBK-217A FIGURE 7.4.4B IMIL-S-192001. KEAKFOTT SEGUMDAHY OATA

MIL-HDBK-217A FIGURE 7.10 .2 (TYPE A)
KEAKFUTT SECONUAKY GATA
KEARFUTT EXPERIENCE


$\stackrel{t}{4}$


## EQUIPMENT -- SULIO STATE KEYBDARD

## 4OC AMLOLENT TENPERATUKE

## FIXED GRUUND ENVIRONMENT

## SUBASSLMDLY. ..... FAILURE KATE


$\stackrel{\stackrel{\rightharpoonup}{\vdots}}{\stackrel{1}{+}}$

## SINGER


RELIABILITY FAILURE MODE \& EFFECTS ANALYSIS


SINGER




## SINGER


RELIABILITY FAILURE MODE \& EFFECTS ANALYSIS
SOLID STATE POTENTIDNIETER

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## APPENDIX I

SCHEMATIC DIAGRAMS
$\stackrel{\square}{\square}$

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FIGURE I-2. SCHEMATIC DIAGRAM SINGLE POLE SWITCH
I-2
$\qquad$


FIGURE I-3. SCHEMATIC DIAGRAM DOUBLE POLE SWITCH

$$
\mathrm{I}-3
$$



FIGURE I-4 SCHEMATIC DIAGRAM 10 POSITION SOLID STATE ROTARY SWITCH



[^0]:    *Trade name of a General Electric Co. product

